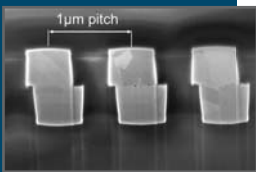
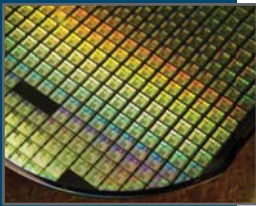


Advanced Packaging Update: Market and Technology Trends

Vol. 4-0119



This issue of the Advanced Packaging Update features special coverage of outsourced semiconductor assembly and test (OSAT) financials through the third quarter of 2018. The report presents options for high-performance packaging, including silicon interposers, fan-out on substrate, and other alternatives. Future 3D alternatives, including 3D stacking with TSVs and fusion bonding, are discussed and a roadmap for adoption is provided. Developments in antenna-in-package (AiP) for 5G are highlighted and a AiP forecast is included. Developments and applications in 3D-printed electronics are also presented.

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